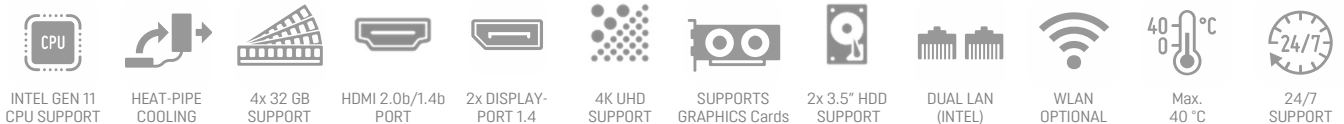


BAREBONE XPC cube SH570R6 Plus

SUPPORTS 10TH/11TH GENERATION INTEL CORE PROCESSORS AND UP TO THREE UHD DISPLAYS

The Shuttle XPC Barebone SH570R6 PLUS shows how discreet a modern PC can look and at the same time how powerful it can be. Its black-brushed aluminium case has barely a volume of 14 litres, but packs everything you need for a high-performance workstation for example. This includes the power of 10th/11th gen. Intel Core processors ("Comet Lake-S" and "Rocket Lake-S"), a dual-slot graphics card, fast M.2 NVMe SSD drives, two 3.5" hard drives in RAID and up to 128 GB of DDR4 memory, plus an optical drive. Even without a dedicated graphics card, up to three UHD displays are supported (if not an F-type CPU is used).



CUBE DESIGN

- Black aluminium chassis ■ Dimensions: 33.2 x 21.5 x 19 cm (LWH), ca. 13.6-litre ■ Operating temperature: 0-40 °C (non-condensing)

OPERATING SYSTEM

- An operating system is not included
- Supports Windows 10/11 and Linux (64-bit)

PROCESSOR SUPPORT

- Socket LGA1200 supports Intel Core i9/i7/i5/i3, Pentium Gold and Celeron processors of Gen. 10 "Comet Lake-S" and **Gen. 11 "Rocket Lake-S"** with up to 125W TDP ■ Includes heatpipe cooling system

CHIPSET & GRAPHICS

- Intel H570 Chipset
- Integrated Intel UHD graphics with triple 4K display support (features depend on processor, "F"-series CPUs lack the integrated graphics)

MEMORY SUPPORT

- Four 288-pin DIMM slots ■ Supports up to 128 GB capacity in total (max. 32 GB each module) ■ Supports DDR4-2666/2933/**3200**

PCI-EXPRESS SLOTS

- 1x PCIe X16 v3/v4 slot supports dual-slot graphics cards up to ca. 28 x 12 x 4 cm (LWH), with 6-pin and 8-pin power connector
- 1x PCIe X4 v3 slot (not usable with dual-slot graphics card)

STORAGE – SATA / M.2

- Bays: 1x 5.25" and 2x 3.5" (1x external), 4x SATA ports (RAID)
- 1x M.2-2280M slot (supports PCIe x4 v3 NVMe or SATA)
- 1x M.2-2230E for optional WLAN (accessory: WLN-M)

CONNECTORS

- HDMI 1.4b/2.0b ■ 2x DisplayPort 1.4 ■ 4x USB 3.2 Gen2 ■ 4x USB 3.2 Gen1 (1x Type-C) ■ 4x USB 2.0 ■ 1x internal USB 2.0 ■ 2x Intel Gigabit LAN (Intel i210AT+i219LM) ■ 5x Audio I/O (2x front, 3x rear)
- Connector for external power button

POWER SUPPLY

- Internal 500W power supply, 80Plus Gold

OPTIONAL ACCESSORIES

- WLAN Kit (WLN-M (ac)/WLN-M1 (ax)) ■ RS232 COM Port (H-RS232)
- Adapter for two 2.5" drives (PHD3) ■ 850W Power Supply (PC850)
- Cable for external power button (CXP01)

Note: Some features marked in red color are only supported in combination with Gen 11 "Rocket Lake-S" processors.

Shuttle XPC cubes with Intel 5xx series chipset

Product	CPU Socket	Chip	Chassis	Drive Bays	LAN	vPro	Power Supply	UPC Code
SH510R4	LGA 1200	H510	R4	5.25" + 2x 3.5"	1x	—	300 W, 80+ Bronze	887993003948
SH570R6	LGA 1200	H570	R6	5.25" + 2x 3.5"	2x	—	300 W, 80+ Bronze	887993003498
SH570R6 Plus	LGA 1200	H570	R6	5.25" + 2x 3.5"	2x	—	500 W, 80+ Gold	887993003870
SH570R8	LGA 1200	H570	R8	4x 3.5"	2x	—	500 W, 80+ Gold	887993003504
SW580R8	LGA 1200	W580	R8	4x 3.5"	4x (2x 2.5G)	Yes	500 W, 80+ Gold	887993004174

REQUIRED COMPONENTS

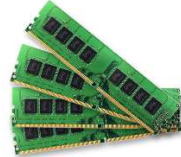
The following components need to be added to make it a fully-configured Mini PC

Shuttle XPC Cube Barebone SH570R6 PLUS (Photo without chassis cover)



LGA1200 Processor

Intel Core Gen 10 "Comet Lake-S" or Gen 11 "Rocket Lake-S"
Core i9 / i7 / i5 / i3, Pentium Gold or Celeron
TDP max. 125 W



Memory Modules

Up to four 288-pin DIMM memory modules, max. 32 GB each
Supports DDR4-3200 clock rate with Gen 11 CPUs
Supports DDR4-2933 clock rate with Core i7/i9 Gen 10 CPUs
Supports DDR4-2666 clock rate with other Gen 10 CPUs



SATA Storage Drives

The drive rack supports three drives:

- 1) 5.25" for an optical drive (SATA)
- 2) 3.5" for a hard disk drive (SATA)
- 3) 3.5" for a hard disk drive (SATA) or a card reader (USB)

Note: use accessory PHD3 to install two 2.5" drives (Hard disks or SSDs) in a 3.5" bay. The mainboard features four SATA ports and one USB 2.0 onboard header.



M.2 SSD (optional)

Supports M.2-2280/2260/2242 formats
Supports SATA or PCIe/NVMe interfaces



PCI-EXPRESS CARDS (optional)

- 1) PCI-E X16 slot (e.g. Single-Slot graphics card)
- 2) PCI-E X4 slot (e.g. Dual 10 Gb network card)

The power consumption of the graphics card must not exceed 300 watts [1]. Max. length is 273 mm. If a dual-slot (double-width) graphics cards is used the second PCI-Express slot will be occupied.



Operating System

Windows 10/11 or Linux (64-bit only)

OPTIONAL ACCESSORIES FROM SHUTTLE



WLAN-Accessory

WLN-M (802.11ac / Wifi 5)
WLN-M1 (802.11ax / Wifi 6)
M.2-2230 card supports
WLAN and Bluetooth
including 2 antennas



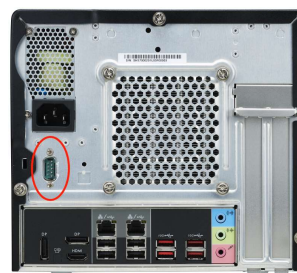
Adapter for 2.5" drives **PHD3**

The PHD3 allows for installation of one or two 63.5 mm (2.5") hard drives or SSDs into a larger 89 mm (3.5") drive bay.



PSU Upgrade **PC850**

850W power supply upgrade kit with 80 PLUS® Platinum efficiency



COM Port Adapter **H-RS232**

The H-RS232 allows for installation of one serial COM port (RS232) in the back panel.



Cable **CXP01**

Cable for external push button switch (without button)

PRODUCT FEATURES



The R6 chassis design: a clean and modern look

R6 is Shuttle's chassis design for the upper mid-range XPCs. Shuttle has always placed great emphasis on the interior and exterior aesthetics of the XPC cubes with the belief that a good blend of style and form factor will enable it to be attractive, versatile, and work well in almost any environment. The case cover is made of aluminium, while the drives and front panel connectors are elegantly hidden by drive doors for superior style and visual appeal.



Integrated Cooling Engine

In order to ensure proper airflow inside such a small case, more advanced cooling technologies have been developed and implemented in the Shuttle XPC. Shuttle's industry-leading I.C.E. heatpipe technology delivers efficient cooling and is exceptionally quiet.



What is a Barebone?

The Shuttle XPC cube Barebone SH570R6 PLUS consists of a stylish case with pre-installed mainboard, power supply unit (PSU) and cables. Despite its small form factor, it offers outstanding connectivity, functionality and performance. For a full PC system, a processor, memory, mass storage and operating system need to be added. Shuttle XPC cube Barebones are completely customisable meaning users can pick certain components on their own to ideally match their individual needs.



Ample space for demanding dual-slot graphics cards

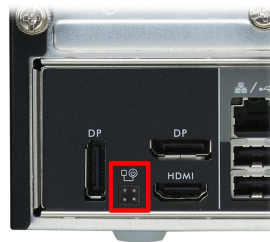
Despite the small housing, the SH570R6 PLUS is capable of running dual-slot (double-height) high-performance PCI Express graphics cards. The system provides additional 6-pin and 8-pin power connectors for more power-hungry graphics cards. The maximum size acceptable for graphics cards is 273 mm x 98 mm x 38 mm. Please refer to the support list for detailed support information at global.shuttle.com.



Triple UHD display support and more

The integrated graphics supports up to three independent monitors at Ultra-HD resolution if not an F-type CPU is used.

This XPC even supports at least five displays in combination with a discrete PCI-Express graphics card, based on the Switchable Graphics feature. Expand your Windows desktop across many monitors, but note it does not support a 2x2 configuration or clone mode with the monitors connected.



External power button by separate remote line

If, because of space constraints (e.g. in case of fixed installation), the machine cannot be switched on by pressing the front power button, it can be powered on by a separate remote line. You will find an appropriate four-pin connector at the back panel of the SH570R6 PLUS (pitch 2.54 mm). Furthermore, this connector provides a Clear CMOS function and +5V DC voltage supply for external devices.

+5V voltage (2) (4) Power Button
Clear CMOS (1) (3) Ground

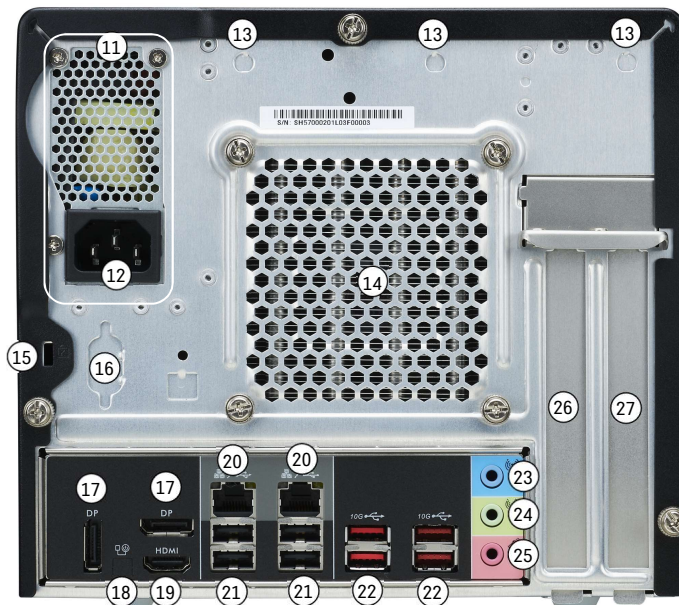
Front and Back Panel

Front panel



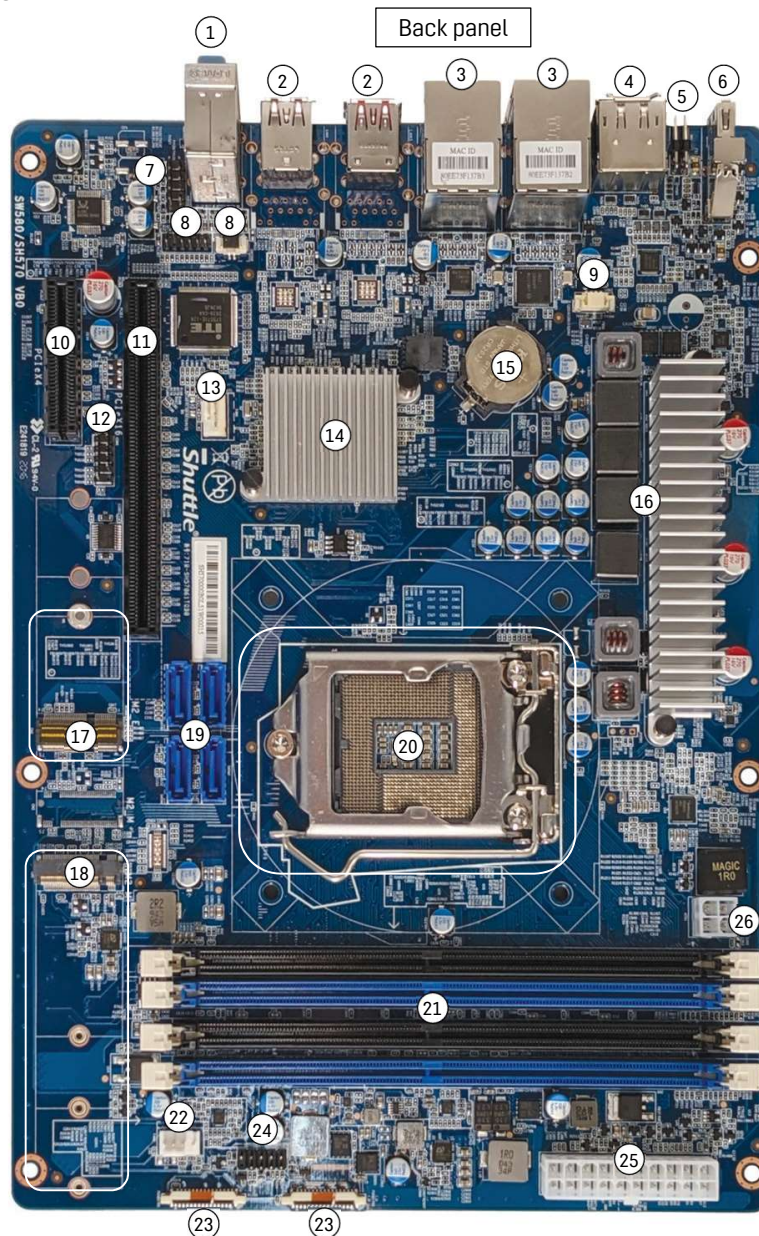
1. 5.25" bay for an optical drive
2. 3.5" bay for HDD, SSD or card reader
3. Eject button for an optical drive
4. Hard disk LED indicator
5. Power LED indicator
6. Power button
7. 3x USB 3.2 Gen 1 Type-A port (5 Gbps)
8. Microphone input
9. Headphones output
10. USB 3.2 Gen 1 Type-C port (5 Gbps)

Back panel



11. Internal power supply unit (PSU)
12. AC power connector
13. 3x perforation for optional WLAN antenna
14. Heat-pipe cooling system
15. Hole for Kensington Lock
16. Perforation for optional COM port
17. DisplayPort 1.4
18. 4-pin connector (2.54 mm pitch) for external power button, Clear CMOS button and 5V DC voltage
19. HDMI 2.0b/1.4b
20. 2x RJ45 Gigabit LAN port
21. 4x USB 2.0 port
22. 4x USB 3.2 Gen 2 Type-A port (10 Gbps)
23. Audio Line-in
24. Audio Line-out
25. Microphone input
26. PCI-Express X16 expansion slot
27. PCI-Express X4 expansion slot

Mainboard



- | | |
|---|---------------------------------------|
| 1. 3x Audio Ports (Line-in / Line-out / Microphone) | 14. Intel H570 chipset with heat sink |
| 2. 4x USB 3.2 Gen 2 Type-A Port (10 Gbps) | 15. CMOS battery |
| 3. 2x RJ45 Gigabit LAN port & 4x USB 2.0 port | 16. CPU voltage regulator area |
| 4. HDMI 2.0b/1.4b port & DisplayPort 1.4 | 17. M2-2230E slot for WLAN card |
| 5. 4-pin connector (2.54 mm pitch) for external power button, Clear CMOS button and 5V DC voltage | 18. M.2-2280M slot for SSD card |
| 6. DisplayPort 1.4 | 19. 4x SATA v3.0 connector |
| 7. Front audio header | 20. LGA1200 processor socket |
| 8. Debug header (reserved) | 21. 4x DIMM memory slot |
| 9. Onboard USB 2.0 connector (4-pin) | 22. Connector for cooling fan (4-pin) |
| 10. PCI-Express X4 expansion slot | 23. Front USB 3.0 header |
| 11. PCI-Express X16 expansion slot | 24. Front buttons / LEDs header |
| 12. Onboard RS232 COM port header (2x5-pin) | 25. ATX power connector (20-pin) |
| 13. Connector for cooling fan (4-pin) | 26. ATX power connector (4-pin) |

Shuttle Product Comparison: SH3xx versus SH5xx

The differences in the newer SH5xx series are marked in **red**.

MODEL	SH310R4V2	SH370R6V2 PLUS	SH370R8	SH510R4	SH570R6 PLUS	SH570R8	SW580R8
CHASSIS	R4 chassis customisable front plate	R6 chassis with front doors for I/O ports	R8 chassis supports four 3.5" hard disks	R4 chassis customisable front plate	R6 chassis with front doors for I/O ports	R8 chassis supports four 3.5" hard disks	R8 chassis supports four 3.5" hard disks
PROCESSOR SUPPORT	Socket LGA1151v2, TDP max. 95 W Code name "Coffee Lake-S" 14 nm – Gen 8 and 9 Supports Celeron, Pentium Gold, Core i3 / i5 / i7 / i9			Socket LGA1200, TDP max. 125 W Code name "Comet/Rocket Lake-S" 14 nm – Gen 10/11 Supports Celeron, Pentium Gold, Core i3 / i5 / i7 / i9			
XEON SUPPORT	–	–	–	–	–	–	Xeon W-Series
CPU COOLING	3 heat-pipes	3 heat-pipes	3 heat-pipes	4 heat-pipes	4 heat-pipes	4 heat-pipes	4 heat-pipes
CHIPSET	Intel H310	Intel H370	Intel H370	Intel H510	Intel H570	Intel H570	Intel W580
Intel vPRO/AMT	–	–	–	–	–	–	Supported
TPM 2.0	Firmware	Firmware	Firmware	Firmware	Firmware	Firmware	Hardware-Chip
OS SUPPORT	Windows 10/11 and Linux (64-bit)			Windows 10/11 and Linux (64-bit)			
DRIVE BAYS	1x 5.25" 2x 3.5"	1x 5.25" 2x 3.5" (1x open)	4x 3.5"	1x 5.25" 2x 3.5"	1x 5.25" 2x 3.5" (1x open)	4x 3.5"	4x 3.5"
SATA PORTS	3	4	4	3	4	4	4
PCI-E SLOTS	PCIe X16 v3.0 PCIe X1 V2.0	PCIe X16 v3.0 PCIe X4 V3.0	PCIe X16 v3.0 PCIe X4 V3.0	PCIe X16 v4.0 PCIe X1 V2.0	PCIe X16 v4.0 PCIe X4 V3.0	PCIe X16 v4.0 PCIe X4 V3.0	PCIe X16 v4.0 PCIe X4 V3.0
MAX. RAM SUPPORT	2x 16 GB DDR4-2933	4x 32 GB DDR4-2933	4x 32 GB DDR4-2933	2x 32 GB DDR4-3200 [*]	4x 32 GB DDR4-3200 [*]	4x 32 GB DDR4-3200 [*]	4x 32 GB DDR4-3200 [*] Supports ECC
GRAPHICS PORTS	HDMI 2.0a DP 1.2, VGA	HDMI 2.0a 2x DP 1.2	HDMI 2.0a 2x DP 1.2	HDMI 2.0b [*] DP 1.4, VGA	HDMI 2.0b [*] 2x DP 1.4	HDMI 2.0b [*] 2x DP 1.4	HDMI 2.0b [*] 2x DP 1.4
M.2 SSD SLOT	1	1	1	1	1	1	2
WLAN SLOT	M.2-2230E			M.2-2230E			
BUTTONS / LEADS	Power-Button, Power LED, HDD LED			Power-Button, Power LED, HDD LED			
USB 3.2 GEN 2	–	4	4	–	4	4	4
USB 3.2 GEN 1	4	4	4	4	4 (1x Type-C)	4 (1x Type-C)	4 (1x Type-C)
USB 2.0	4	4	4	4	4	4	4
USB 2.0 onboard	1	2	2	1	1	1	1
1G NETWORK	1x Intel i219LM	2x Intel 211	2x Intel 211	1x Intel i219LM	1x Intel i210AT 1x Intel i219LM	1x Intel i210AT 1x Intel i219LM	1x Intel i210AT 1x Intel i219LM
2.5G NETWORK	–	–	–	–	–	–	2x RTL 8125b
AUDIO	Mic-Input, Headphone Output and 6-channel Line-Out			Mic-Input, Headphone Output and 6-channel Line-Out			
OPTIONAL ACCESSORIES	WLAN Kit: WLN-M (ac) / WLN-M1 (ax) COM-Port: H-RS232 3.5"/2.5" Adapter: PHD3			WLAN Kit: WLN-M (ac) / WLN-M1 (ax) COM-Port: H-RS232 3.5"/2.5" Adapter: PHD3 Cable for ext. power button: CXP01 850W-power supply: PC850			
POWER SUPPLY	300W 80+ Bronze	300W Plus: 500W	500 W 80+ Gold	300W 80+ Bronze	300W Plus: 500W	500 W 80+ Gold	500 W 80+ Gold

[*] Note: SH5xx-Series supports PCIe X16 **V4** slot, DDR4-**3200** and HDMI **2.0b** with **Gen. 11** Processors "**Rocket Lake**", but only PCIe X16 **V3** slot, DDR4-**2666/2933** and HDMI **1.4b** with **Gen. 10** Processors "**Comet Lake**".

SHUTTLE XPC CUBE BAREBONE SH570R6 PLUS – SPECIFICATIONS

CHASSIS	<p>Black aluminium chassis</p> <p>Front panel: glossy plastic with horizontal line textures</p> <p>Front doors for I/O ports and storage drives</p> <p>Kensington Security Slot at the backpanel (also called K-Slot or Kensington lock) as a part of an anti-theft system</p> <p>Dimensions: 33.2 x 21,5 x 19.0 cm (LWH without feet) = 13.6 litre</p> <p>Height with rubber feet: 19.7 cm</p> <p>Weight: 3.5 kg net / 4.5 kg gross</p>
MAINBOARD / CHIPSET	<p>Mainboard with Shuttle form factor, proprietary design for XPC SH570R6 PLUS</p> <p>Chipset/Southbridge: Intel® H570</p> <p>Passive chipset cooling with heat sink</p> <p>The Northbridge is integrated in the processor.</p> <p>Solid Capacitors for sensitive areas provide excellent heat resistance for enhanced system durability</p>
BIOS	<p>AMI BIOS, SPI Interface, 16 MB Flash-EEPROM</p> <p>Supports Hardware Monitoring, Watch Dog</p> <p>Supports Power Fail Resume</p> <p>Supports Firmware-TPM (fTPM) v2.0</p> <p>Supports boot up from external USB flash memory</p> <p>Supports Unified Extensible Firmware Interface (UEFI)</p>
POWER SUPPLY	<p>Built-in 500 Watt mini switching power supply [1]</p> <p>AC input voltage: 100~240V, 50~60 Hz</p> <p>80 PLUS Gold compliant</p> <p>Active PFC circuit (Power Factor Correction)</p> <p>ATX main power connectors: 2x10 and 2x2-pin</p> <p>Graphics power connector: 6-pin and 8-pin</p> <p>Other connectors: 4x SATA, 2x Molex</p>
OPERATING SYSTEM	<p>This system comes without operating system.</p> <p>It is compatible with Windows 10/11 and Linux (64-bit)</p>
PROCESSOR SUPPORT	<p>Processor Socket LGA 1200</p> <p>Supports Intel Core i9 / i7 / i5 / i3, Pentium Gold and Celeron processors</p> <p>Supports the 10th and 11th generation Intel Core processors, code name "Comet Lake-S" and "Rocket Lake-S" in 14++ nm process technology</p> <p>Maximum supported processor power consumption (TDP) = 125 W</p> <p>Up to 10 CPU cores, 20 threads and 20 MB of L3 cache</p> <p>Does not support the unlock-function of Intel K-Series processors.</p> <p>The processor integrates PCI-Express, memory controller and the graphics engine on the same die.</p> <p>However, processors with "F" identifier do not support integrated graphics [3] (performance features depending on processor type)</p> <p>Please refer to the support list for detailed processor support information at global.shuttle.com.</p>
HEAT-PIPE COOLING	<p>Shuttle I.C.E. (Integrated Cooling Engine)</p> <p>advanced I.C.E. heatpipe technology, linear-controlled 92mm fan</p> <p>SilentX cooling and noise reduction technology with Active Airflow</p>
MEMORY SUPPORT	<p>4x 288-pin slot</p> <p>Supports DDR4 memory at 1.2V</p> <p>Supports Dual Channel mode</p> <p>Supports max. 32 GB per DIMM, maximum total size of 128 GB</p> <p>The maximum DDR4 clock frequency depends on the processor type used:</p> <ul style="list-style-type: none"> - Gen. 11 "Rocket Lake" supports DDR4-3200 (PC4-25600U) - Gen. 10 "Comet Lake" Core i7/i9 supports DDR4-2933 (PC4-23433U) - other "Comet Lake" support DDR4-2666 (PC4-21300U)
PCI-E EXPANSION SLOTS	<p>1x PCI-Express x16 v4.0 slot (supports PCI-Express v3.0 with Gen. 10 "Comet Lake" processors)</p> <p>1x PCI-Express x4 v3.0 slot, open-ended</p> <p>Supports dual-slot (double-width) graphics cards (occupies the second PCI-Express slot)</p> <p>The maximum size acceptable for display cards is 273 x 98 x 38 mm.</p> <p>Graphics power connector: 6-pin and 8-pin [1]</p>

INTEGRATED GRAPHICS (OPTIONAL [3])	<p>The features of the integrated Intel UHD graphics function depend on the processor type used. Certain processor models do not support integrated graphics [3] The PC features three video outputs which support 2160p/60 UHD resolution: - 1x HDMI v2.0b (only HDMI v1.4b with Gen. 10 "Comet Lake" Prozessoren) - 2x DisplayPort v1.4 Supports displays with 4K Ultra HD resolution at 3840 x 2160 (2160p/60) Supports three independent displays with the integrated graphics function Supports more displays in combination with a discrete graphics card Hardware video decoding/encoding DisplayPort and HDMI support multi-channel digital audio over the same cable</p>
DRIVE BAYS	<p>Storage bays: 1 x 5.25" (external), 2 x 3.5" (1x internal, 1x external) Using the optional accessory PHD3 two 2.5" drives can be installed into one 3.5" bay.</p>
SATA CONNECTORS	<p>4x Serial ATA 6G connector onboard (rev. 3.0, max. 6 Gbit/s) Supports Intel Rapid Storage Technology (RST) with RAID 0/1/5/10, JBOD)</p>
M.2-2280M SSD SLOT	<p>The M.2 2280M slot provides the following interfaces: - PCI-Express Gen. 3.0 X4, supports NVMe - SATA v3.0 (max. 6 Gbps) It supports M.2 cards with a width of 22 mm and a length of 42, 60 or 80 mm (type 2242, 2260, 2280). Supports M.2 SSDs with SATA or PCI-Express interface</p>
M.2-2230E SLOT FOR WLAN CARDS	<p>Interfaces: PCI-Express Gen. 3.0 X1 und USB 2.0 Supports M.2 cards with a width of 22 mm and a length of 30 mm (type 2230) Supports WLAN extension cards (optional Shuttle accessory: WLN-M)</p>
HD AUDIO	<p>Audio Codec: Realtek ALC897, 5.1 channel Three analog audio connectors (3.5 mm) on the backpanel: Line-in (blue), line-out (green) and microphone input (pink) shared with 5.1 channel line-out (front, rear, center/bass) Front panel: microphone input and head phone output (line-out)</p>
DUAL GIGABIT LAN	<p>Dual Gigabit network with two RJ45 ports 1x Intel i210AT - Ethernet Controller with MAC, PHY and PCIe interface 1x Intel i219LM - PHY connected to the MAC of the processor Supports 10 / 100 / 1.000 MBit/s operation Supports WAKE ON LAN (WOL) Supports network boot by Preboot eXecution Environment (PXE) Supports Teaming mode [4]</p>
FRONT PANEL CONNECTORS	<p>Microphone input (3.5 mm) Headphones output (3.5 mm) 1x USB 3.2 Gen 1 (5 Gbps), Type C 3x USB 3.2 Gen 1 (5 Gbps), Type A, blue Power button Power indicator (Blue LED) Hard disk drive indicator (Yellow LED)</p>
BACK PANEL CONNECTORS	<p>1x HDMI 2.0b (HDMI 1.4b with Gen. 10 "Comet Lake" processor) 2x DisplayPort 1.4 [2] 4x USB 3.2 Gen 2 (10 Gbps), Type A, red 4x USB 2.0 (Type A, black) 2x Gigabit LAN (RJ45) Audio Line-out (3.5 mm) Audio Line-in (3.5 mm) Microphone Input (3.5 mm) 1x 4-pin connector (2.54 mm pitch) supports: - external power on button - Clear CMOS function - +5V DC voltage for external components Optional: Serial RS232 port (Accessory: "H-RS232") 3x perforation for optional WLAN antennas (Accessory: "WLN-M")</p>
OTHER ONBOARD CONNECTORS	<p>Occupied front panel connectors for USB, audio, buttons, LEDs 1x RS232 serial interface (2x5 pin header) 2x fan connectors (4-pin header) 1x USB 2.0 (4-pin header)</p>

SUPPLIED ACCESSORIES	Multi-language XPC Installation Guide (EN, DE, FR, ES, JP, KR, SC, TC) Windows 64-bit driver disk 2x Serial ATA cables AC Power Cord (with protective-earth contacts) Heatsink Compound Protector cap for the CPU socket (do not use if heatpipe or fan is mounted) Bag with screws
OPTIONAL ACCESSORIES	Back panel adapter for serial RS232 port (H-RS232) WLAN kit supports WLAN and Bluetooth with two external antennas (WLN-M (802.11ac) and WLN-M1 (802.11ax)) Adapter for 2.5" drives such as SSDs (PHD3) Adapter cable for external power button (CXP01) 850W power supply (PC850)
ENVIRONMENTAL SPECIFICATIONS	Permissible ambient temperature during operation: 0~40 °C Relative humidity: 10~90 %.
CERTIFICATIONS / COMPLIANCE	EMI: FCC, CE, BSMI, C-Tick Safety: ETL, CB, BSMI Other: RoHS, Energy Star 5.0, ErP This device is classed as a technical information equipment (ITE) in class B and is intended for use in living room and office. The CE-mark approves the conformity by the EU directives: (1) 2014/30/EU relating to electromagnetic compatibility (EMC), (2) 2014/35/EU relating to Electrical Equipment designed for use within certain voltage limits (LVD), (3) 2009/125/EC relating to ecodesign requirements for energy-related products (ErP).

[1] Online Power Calculator

The PCI Express x16 slot provides a maximum of 75 Watts to the graphics card, plus 75 Watts and 150 Watts from the 6-pin and 8-pin connector of the power supply - so the power consumption of the graphics card must not exceed 300 watts. The processor may have a maximum TDP of 125 Watts. If powerful PC components are used, then check with the "Power Supply Calculator" whether the built-in 500 Watt power supply supports this configuration, see: <http://global.shuttle.com/support/power>. Please also refer to the support list for detailed processor and graphics cards support information at <http://global.shuttle.com>.

[2] How to convert DisplayPort to HDMI/DVI

The DisplayPort output can be converted to HDMI or DVI by an additional, passive adapter cable. For example:

DELOCK 82590: 1 m, DisplayPort (male, 20p) to HDMI-A (male, 19p)

DELOCK 82435: 5 m, DisplayPort (male, 20p) to DVI-D (male, 24p)

The integrated graphics automatically detects the connected display and puts out the appropriate electric signal - either DisplayPort (without an adapter) or HDMI/DVI (with an adapter).

However, a monitor with a DisplayPort connector cannot be connected to the HDMI port with a simple, passive adapter.

[3] Integrated graphics is optional

Processors with model numbers ending with "F" (z.B. Intel Core i5-11600F) do not support integrated graphics, so that the graphics outputs of the Shuttle XPC have no function. In this case, an additional discrete PCIe graphics card is mandatory.

[4] Teaming Mode

The teaming function allows you to group both available network adapters together to function as a single adapter. The benefit of this approach is that it enables load balancing and failover.

10TH GENERATION INTEL CORE DESKTOP PROCESSOR FAMILY

Socket LGA1200 14 nm "Comet Lake S" and "Comet Lake Refresh" processor overview (Date: August 2021)

PROCESSOR	MODEL	CORES/ THREADS	CPU CLOCK	TURBO BOOST CLOCK (2.0)	SMART CACHE	TDP	MEMORY SUPPORT	GRAPHICS ENGINE
Core™ i9	10900K	10/20	3.7 GHz	5.1 GHz	20 MB	125 W	DDR4-2933	UHD 630 (1.2 GHz)
	10900KF	10/20	3.7 GHz	5.1 GHz	20 MB	125 W	DDR4-2933	None
	10900	10/20	2.8 GHz	5.0 GHz	20 MB	65 W	DDR4-2933	UHD 630 (1.2 GHz)
	10900F	10/20	2.8 GHz	5.0 GHz	20 MB	65 W	DDR4-2933	None
	10900T	10/20	1.9 GHz	4.5 GHz	20 MB	35 W	DDR4-2933	UHD 630 (1.2 GHz)
	10850K	10/20	3.6 GHz	5.0 GHz	20 MB	125 W	DDR4-2933	UHD 630 (1.2 GHz)
Core™ i7	10700K	8/16	3.8 GHz	5.0 GHz	16 MB	125 W	DDR4-2933	UHD 630 (1.2 GHz)
	10700KF	8/16	3.8 GHz	5.0 GHz	16 MB	125 W	DDR4-2933	None
	10700	8/16	2.9 GHz	4.7 GHz	16 MB	65 W	DDR4-2933	UHD 630 (1.2 GHz)
	10700F	8/16	2.9 GHz	4.7 GHz	16 MB	65 W	DDR4-2933	None
	10700T	8/16	2.0 GHz	4.4 GHz	16 MB	35 W	DDR4-2933	UHD 630 (1.2 GHz)
Core™ i5	10600K	6/12	4.1 GHz	4.8 GHz	12 MB	125 W	DDR4-2666	UHD 630 (1.2 GHz)
	10600KF	6/12	4.1 GHz	4.8 GHz	12 MB	125 W	DDR4-2666	None
	10600	6/12	3.3 GHz	4.8 GHz	12 MB	65 W	DDR4-2666	UHD 630 (1.2 GHz)
	10600T	6/12	2.4 GHz	4.0 GHz	12 MB	35 W	DDR4-2666	UHD 630 (1.2 GHz)
	10500	6/12	3.1 GHz	4.5 GHz	12 MB	65 W	DDR4-2666	UHD 630 (1.15 GHz)
	10500T	6/12	2.3 GHz	3.8 GHz	12 MB	35 W	DDR4-2666	UHD 630 (1.1 GHz)
	10400	6/12	2.9 GHz	4.3 GHz	12 MB	65 W	DDR4-2666	UHD 630 (1.1 GHz)
	10400F	6/12	2.9 GHz	4.3 GHz	12 MB	65 W	DDR4-2666	None
Core™ i3	10400T	6/12	2.0 GHz	3.6 GHz	12 MB	35 W	DDR4-2666	UHD 630 (1.1 GHz)
	10325	4/8	3.9 GHz	4.7 GHz	8 MB	65 W	DDR4-2666	UHD 630 (1.15 GHz)
	10320	4/8	3.8 GHz	4.6 GHz	8 MB	65 W	DDR4-2666	UHD 630 (1.15 GHz)
	10305	4/8	3.8 GHz	4.5 GHz	8 MB	65 W	DDR4-2666	UHD 630 (1.15 GHz)
	10305T	4/8	3.8 GHz	4.5 GHz	8 MB	65 W	DDR4-2666	UHD 630 (1.1 GHz)
	10300	4/8	3.7 GHz	4.4 GHz	8 MB	65 W	DDR4-2666	UHD 630 (1.15 GHz)
	10300T	4/8	3.0 GHz	3.9 GHz	8 MB	35 W	DDR4-2666	UHD 630 (1.1 GHz)
	10105F	4/8	3.7 GHz	4.4 GHz	6 MB	65 W	DDR4-2666	None
	10105	4/8	3.7 GHz	4.4 GHz	6 MB	65 W	DDR4-2666	UHD 630 (1.1 GHz)
	10105T	4/8	3.0 GHz	3.9 GHz	6 MB	35 W	DDR4-2666	UHD 630 (1.1 GHz)
	10100	4/8	3.6 GHz	4.3 GHz	6 MB	65 W	DDR4-2666	UHD 630 (1.1 GHz)
	10100F	4/8	3.6 GHz	4.3 GHz	6 MB	65 W	DDR4-2666	None
10100T	4/8	3.0 GHz	3.8 GHz	6 MB	35 W	DDR4-2666	UHD 630 (1.1 GHz)	
Pentium® Gold	G6605	2/4	4.3 GHz	-	4 MB	58 W	DDR4-2666	UHD 630 (1.1 GHz)
	G6600	2/4	4.2 GHz	-	4 MB	58 W	DDR4-2666	UHD 630 (1.1 GHz)
	G6505	2/4	4.2 GHz	-	4 MB	58 W	DDR4-2666	UHD 630 (1.1 GHz)
	G6500	2/4	4.1 GHz	-	4 MB	58 W	DDR4-2666	UHD 630 (1.1 GHz)
	G6500T	2/4	3.5 GHz	-	4 MB	35 W	DDR4-2666	UHD 630 (1.05 GHz)
	G6405	2/4	4.1 GHz	-	4 MB	58 W	DDR4-2666	UHD 610 (1.05 GHz)
	G6405T	2/4	3.5 GHz	-	4 MB	35 W	DDR4-2666	UHD 610 (1.05 GHz)
	G6400	2/4	4.0 GHz	-	4 MB	58 W	DDR4-2666	UHD 610 (1.05 GHz)
G6400T	2/4	3.4 GHz	-	4 MB	35 W	DDR4-2666	UHD 610 (1.05 GHz)	

PROCESSOR	MODEL	CORES/ THREADS	CPU CLOCK	TURBO BOOST CLOCK (2.0)	SMART CACHE	TDP	MEMORY SUPPORT	GRAPHICS ENGINE
Celeron®	G5925	2/2	3.6 GHz	–	4 MB	58 W	DDR4-2666	UHD 610 (1.05 GHz)
	G5920	2/2	3.5 GHz	–	2 MB	58 W	DDR4-2666	UHD 610 (1.05 GHz)
	G5905	2/2	3.5 GHz	–	4 MB	58 W	DDR4-2666	UHD 610 (1.05 GHz)
	G5905T	2/2	3.3 GHz	–	4 MB	35 W	DDR4-2666	UHD 610 (1.05 GHz)
	G5900	2/2	3.4 GHz	–	2 MB	58 W	DDR4-2666	UHD 610 (1.05 GHz)
	G5900T	2/2	3.2 GHz	–	2 MB	35 W	DDR4-2666	UHD 610 (1.05 GHz)

K = unlocked, T = Power optimized lifestyle, F = without integrated graphics, TDP = Thermal Design Power (max. Power Consumption).

Note: The Shuttle XPC cube Barebone SH570R6 Plus does not support the Unlock-function of Intel K-Series processors.

Intel processors without integrated graphics can be identified by their model name ending on "F". When using this CPU, a graphics card is required.

Please refer to the support list for detailed processor support information at global.shuttle.com.

11TH GENERATION INTEL CORE DESKTOP PROCESSOR FAMILY

Socket LGA1200 14 nm "Rocket Lake S" processor overview (Date: August 2021)

PROCESSOR	MODEL	CORES/ THREADS	CPU CLOCK	TURBO BOOST CLOCK (2.0)	SMART CACHE	TDP	MEMORY SUPPORT	GRAPHICS ENGINE MAX. CLOCK / EUs
Core™ i9	11900K	8/16	3.5 GHz	5.3 GHz	16 MB	125 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11900KF	8/16	3.5 GHz	5.3 GHz	16 MB	125 W	DDR4-3200	None
	11900	8/16	2.5 GHz	5.2 GHz	16 MB	65 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11900F	8/16	2.5 GHz	5.2 GHz	16 MB	65 W	DDR4-3200	None
	11900T	8/16	1.5 GHz	4.9 GHz	16 MB	35 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
Core™ i7	11700K	8/16	3.6 GHz	5.0 GHz	16 MB	125 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11700KF	8/16	3.6 GHz	5.0 GHz	16 MB	125 W	DDR4-3200	None
	11700	8/16	2.5 GHz	4.9 GHz	16 MB	65 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11700F	8/16	2.5 GHz	4.9 GHz	16 MB	65 W	DDR4-3200	None
	11700T	8/16	1.4 GHz	4.6 GHz	16 MB	35 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
Core™ i5	11600K	6/12	3.9 GHz	4.9 GHz	12 MB	125 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11600KF	6/12	3.9 GHz	4.9 GHz	12 MB	125 W	DDR4-3200	None
	11600	6/12	2.8 GHz	4.8 GHz	12 MB	65 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11600T	6/12	1.7 GHz	4.1 GHz	12 MB	35 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11500	6/12	2.7 GHz	4.6 GHz	12 MB	65 W	DDR4-3200	UHD 750 (1.3 GHz, 32 EUs)
	11500T	6/12	1.5 GHz	3.9 GHz	12 MB	35 W	DDR4-3200	UHD 750 (1.2 GHz, 32 EUs)
	11400	6/12	2.6 GHz	4.4 GHz	12 MB	65 W	DDR4-3200	UHD 730 (1.3 GHz, 24 EUs)
	11400F	6/12	2.6 GHz	4.4 GHz	12 MB	65 W	DDR4-3200	None
	11400T	6/12	1.3 GHz	3.7 GHz	12 MB	35 W	DDR4-3200	UHD 730 (1.2 GHz, 24 EUs)

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